



## Material Content Data Sheet



Sales Product Name	SAK-XC2365A-104F80L AA			Issued		1. June 2017		
MA#	MA001589732							
Package	PG-LQFP-100-8			Weight*		746.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	38.601	5.17	5.17	51743	51743
leadframe	inorganic material	phosphorus	7723-14-0	0.067	0.01		90	
	non noble metal	zinc	7440-66-6	0.270	0.04		362	
	non noble metal	iron	7439-89-6	5.396	0.72		7233	
	non noble metal	copper	7440-50-8	219.094	29.37	30.14	293685	301370
wire	noble metal	gold	7440-57-5	2.820	0.38	0.38	3780	3780
encapsulation	organic material	carbon black	1333-86-4	2.301	0.31		3085	
	plastics	epoxy resin	-	62.137	8.33		83291	
	inorganic material	silicondioxide	60676-86-0	395.833	53.06	61.70	530596	616972
leadfinish	non noble metal	tin	7440-31-5	8.282	1.11	1.11	11102	11102
plating	noble metal	silver	7440-22-4	1.060	0.14	0.14	1421	1421
glue	plastics	epoxy resin	-	2.539	0.34		3403	
	noble metal	silver	7440-22-4	7.616	1.02	1.36	10209	13612
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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